



Customer Information Notification

202203024I : LFET1T 65V Technology Qualified in NXP ICN8 Manufacturing Site

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 07, 2022 **Effective date:** Apr 08, 2022

Here is your personalized notification about a NXP general announcement.
For detailed information we invite you to view this notification online

Management summary

Notification to inform customers about the successful qualification of LFET1T 65V technology products in NXP ICN8 Wafer Manufacturing Site, with new orderable part numbers.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other: Data Sheet Update (New Orderable Part Numbers) | | | |

PCN Overview

Description

NXP Semiconductors announces the qualification of NXP ICN8 Fab, located in Nijmegen, Netherlands, as the Manufacturing Center of Excellence for the LFET1T 65V technology products associated with this notification. This site change affects the LFET1T power die only of the dual die product - no change to the control die, or Assembly / Test sites or processes. The new ICN8 sourced LFET1T products have completed qualification, and can now be ordered using the new part numbers per the attached information.

NXP ICN8 Fab was successfully qualified adhering to NXP specifications and AEC-Q100 rev.H / AEC-Q101 rev.D1 requirements.

Please reference the attached presentation for additional details on this qualification.

Please refer to the PPAP of each device qualified for additional details.

New data sheet MC06XS4200 Rev 6.0 may be obtained at <https://www.nxp.com/docs/en/data-sheet/MC06XS4200.pdf>

New data sheet MC10XS4200 Rev 8.0 may be obtained at <https://www.nxp.com/docs/en/data-sheet/MC10XS4200.pdf>

Please reference the new data sheet revision history sections for a complete list of changes.

In September 2020, NXP Semiconductors announced the decision to scale down operations at our Oak Hill Fab, located in Austin, Texas, through General Notification 202009009G. NXP LFET1T 65V technology products are directly impacted by this Oak Hill Fab scale down activity. Therefore, customers are highly encouraged to migrate to the ICN8 fab new part numbers, as existing / old part numbers have undergone End-of-Life / Discontinuation, with Last Time Buy Date 01-Dec-2021 and Last Ship Date 01-Dec-2023.

In calendar year 2022, additional NXP LFET1T 65V technology products will be qualified at ICN8 Fab, and a Customer Information Notification relaying details of the new products will be distributed at that time to all affected customers.

Reason

Qualification of LFET1T 65V technology products in NXP ICN8 Fab, located in Nijmegen, Netherlands, is required for customer supply assurance with the announcement of the scale down operations at our Oak Hill Fab.

Identification of Affected Products

Replacement part type created, see Parts Affected list
New part numbers are created for ICN8 wafer fab products

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional documents: [view online](#)

Related Notification

Notification	Issue Date	Effective Date	Title
202009009G	Sep 11, 2020		NXP Semiconductors Will Scale Down Operations at Oak Hill Fab

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name SAMUEL LESNAKOWSKI
Position Quality Engineer
e-mail address samuel.lesnakowski@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply .

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2022 NXP Semiconductors. All rights reserved.

Changed Orderable Part	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part	12NC New	Product Type New	Product Description New	Product Line	Notes
MC06S4200FK	93407052357	MC06S4200FK	24V 6inDhm Dual high side	HPwrDFN23	SOT193B-1	DOD	No	MC06S4200FK	93407219557	MC06S4200CFK	24V 6inDhm Dual high side	BLC3	Oah Hill Fab product MC06S4200FK replaced by ICN8 Fab product MC06S4200CFK
MC06S4200FKR2	93407052357	MC06S4200FKR2	24V 6inDhm Dual high side	HPwrDFN23	SOT193B-1	DOD	No	MC06S4200CFKR2	93407219557	MC06S4200CFKR2	24V 6inDhm Dual high side	BLC3	Oah Hill Fab product MC06S4200FKR2 replaced by ICN8 Fab product MC06S4200CFKR2
MC06S4200BPK	93407050557	MC06S4200BPK	24V 6inDhm Dual high side	HPwrDFN23	SOT193B-1	DOD	No	MC06S4200BPK	93407242257	MC06S4200BPK	SPO06 PHASE1 ICN8	BLC3	Oah Hill Fab product MC06S4200BPK replaced by ICN8 Fab product MC06S4200BPK
MC06S4200BPKR2	93407050557	MC06S4200BPKR2	24V 6inDhm Dual high side	HPwrDFN23	SOT193B-1	DOD	No	MC06S4200BPKR2	93407242257	MC06S4200BPKR2	SPO06 PHASE1 ICN8	BLC3	Oah Hill Fab product MC06S4200BPKR2 replaced by ICN8 Fab product MC06S4200BPKR2
MC10S4200FK	93407048557	MC10S4200FK	24V Dual 10mDhm HS Sw	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200CFK	93407219757	MC10S4200CFK	24V Dual 10mDhm HS Sw	BLC3	Oah Hill Fab product MC10S4200FK replaced by ICN8 Fab product MC10S4200CFK
MC10S4200FKR2	93407048557	MC10S4200FKR2	24V Dual 10mDhm HS Sw	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200CFKR2	93407219757	MC10S4200CFKR2	24V Dual 10mDhm HS Sw	BLC3	Oah Hill Fab product MC10S4200FKR2 replaced by ICN8 Fab product MC10S4200CFKR2
MC10S4200BPK	93407064578	MC10S4200BPK	SFD10 phaseII	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200BPK	93407241557	MC10S4200BPK	SFD10 PHASE1 ICN8	BLC3	Oah Hill Fab product MC10S4200BPK replaced by ICN8 Fab product MC10S4200BPK
MC10S4200BPKR2	93407064578	MC10S4200BPKR2	SFD10 phaseII	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200BPKR2	93407241557	MC10S4200BPKR2	SFD10 PHASE1 ICN8	BLC3	Oah Hill Fab product MC10S4200BPKR2 replaced by ICN8 Fab product MC10S4200BPKR2
MC10S4200BPK	93407060757	MC10S4200BPK	SFD10 phaseIII	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200BPK	93407241357	MC10S4200BPK	SFD10 Trim config ICN8	BLC3	Oah Hill Fab product MC10S4200BPK replaced by ICN8 Fab product MC10S4200BPK
MC10S4200BPKR2	93407060757	MC10S4200BPKR2	SFD10 phaseIII	HPwrDFN23	SOT193B-1	DOD	No	MC10S4200BPKR2	93407241357	MC10S4200BPKR2	SFD10 Trim config ICN8	BLC3	Oah Hill Fab product MC10S4200BPKR2 replaced by ICN8 Fab product MC10S4200BPKR2